

In the Specification

Please make the following changes to the originally filed Specification at page 4, line 17:

Fig. 18 is a view of a substrate fragment processed ~~[[ia]]~~ in accordance with the invention.

Please make the following changes to the originally filed Specification at page 13, line 24:

The illustrated projecting apexes actually project in to half-way inter the thickness of the bonding pads, a distance of approximately ~~on-half~~ one-half "A".